Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_{RM}	150	V
RMS Reverse Voltage	$V_{R(RMS)}$	106	V
Average Rectified Output Current (See Figure 1)	I_O	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	42	A
Repetitive Peak Avalanche Power (1μS, +25°C)	P_{ARM}	6,000	W

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance Junction to Soldering (Note 6)	$R_{\theta JS}$	3	°C/W
Thermal Resistance Junction to Ambient (Note 7)	$R_{\theta JA}$	119	
Thermal Resistance Junction to Ambient (Note 8)	$R_{\theta JA}$	88	
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 9)	$V_{(BR)R}$	150	-	-	V	I_R = 100μA
Forward Voltage Drop	V_F	-	-	0.70	V	I_F = 1.0A, T_J = +25ºC
		-	-	0.56		I_F = 1.0A, T_J = +125ºC
Leakage Current (Note 9)	I_R	-	-	0.1	mA	V_R = 150V, T_J = +25ºC
		-	-	10	mA	V_R = 150V, T_J = +125ºC

Notes:
6. Theoretical $R_{\theta JS}$ calculated from the top center of the die straight down to the PCB cathode tab solder junction.
7. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com/datasheets/ap02001.pdf. T_A = 25ºC
8. Polymide PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com
9. Short duration pulse test used to minimize self-heating effect.

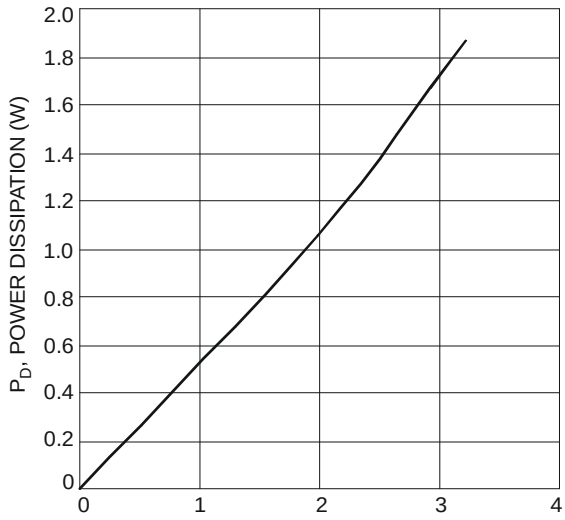


Fig. 1 Forward Power Dissipation

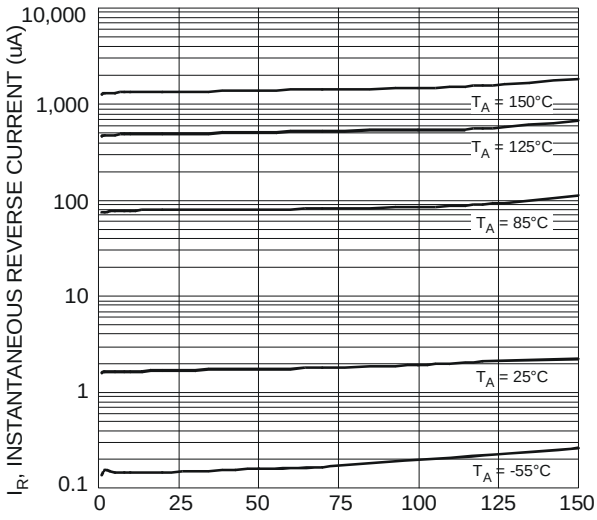


Fig. 2 Typical Reverse Characteristics

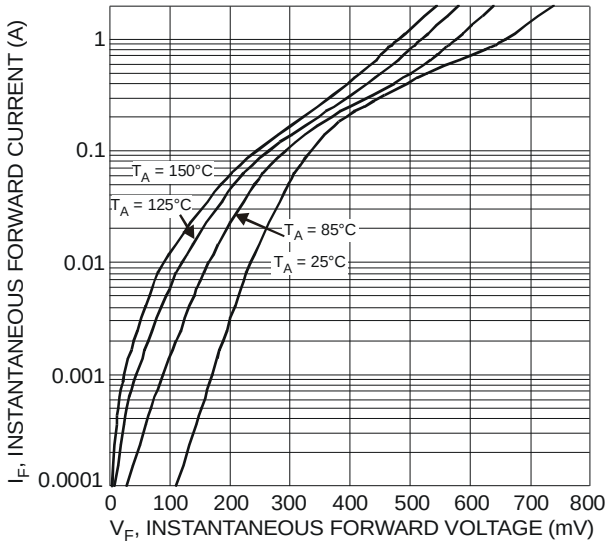


Fig. 3 Typical Forward Characteristics

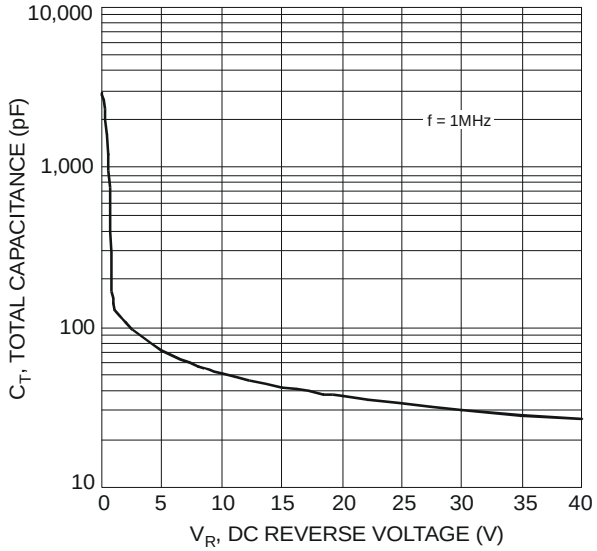


Fig. 4 Total Capacitance vs. Reverse Voltage

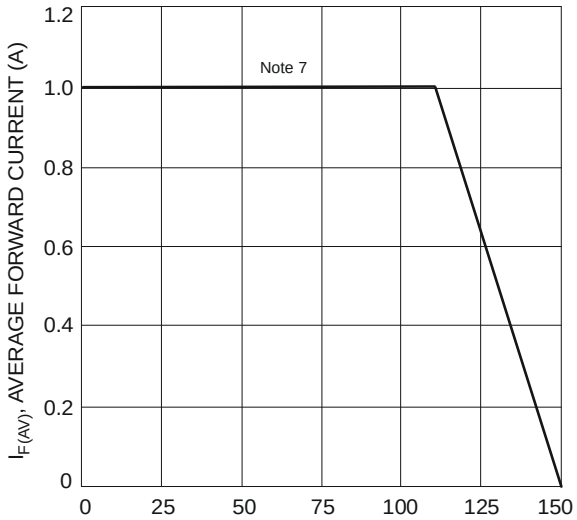


Fig. 5 DC Forward Current Derating Curve

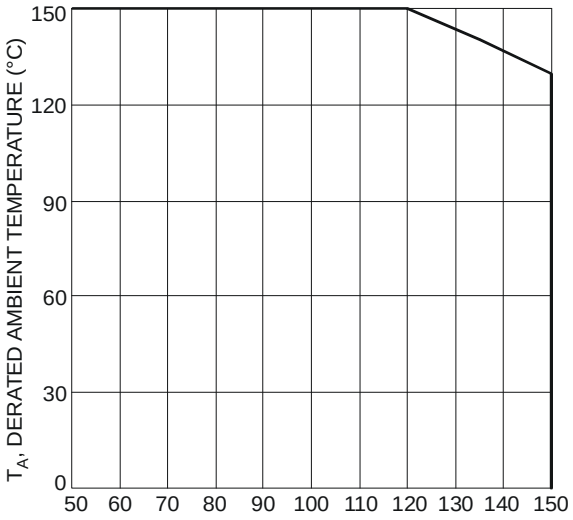


Fig. 6 Operating Temperature Derating

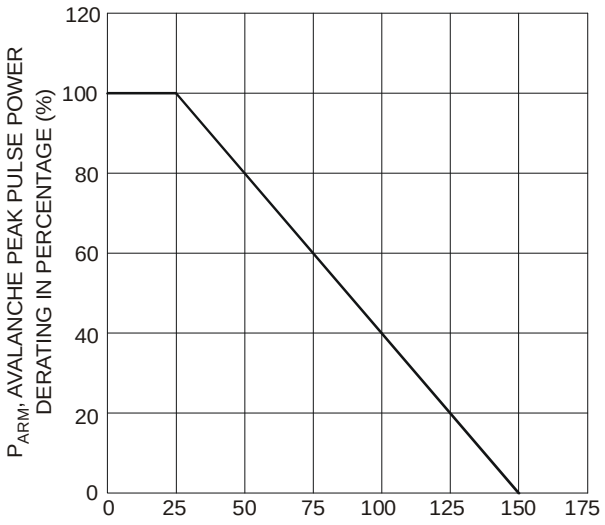


Fig. 7 Pulse Derating Curve

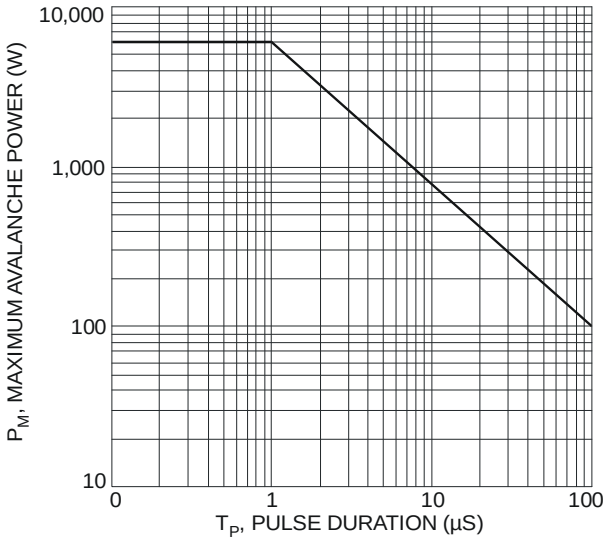
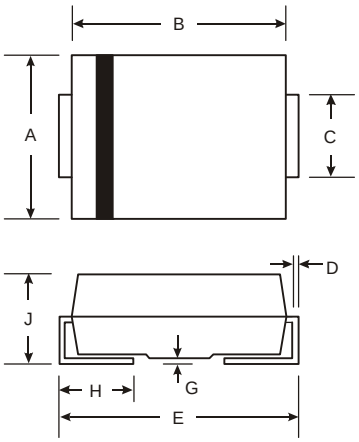


Fig. 8 Maximum Avalanche Power vs. Pulse Duration

Package Outline Dimensions

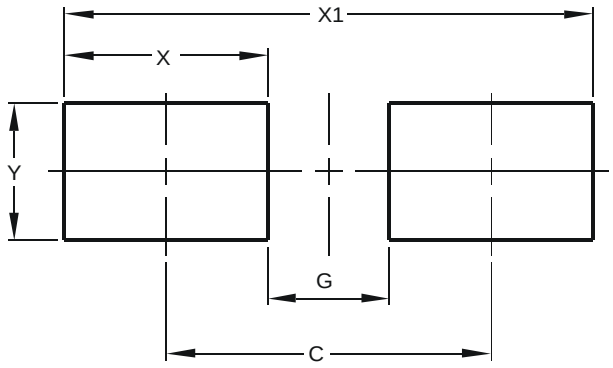
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SMA		
Dim	**Min**	**Max**
A	2.29	2.92
B	4.00	4.60
C	1.27	1.63
D	0.15	0.31
E	4.80	5.59
G	0.05	0.20
H	0.76	1.52
J	2.01	2.30
All Dimensions in mm		

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

www.diodes.com